



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSOP-6					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	480	240 000	200 °C + N2	0	0.00
HAST	1166	116 600	130 °C, 85 % RH	0	0.00
Power Cycle	492	7 380 000	DELTA T _J = 100 °C	0	0.00
Pressure Pot	1166	130 752	121°, 15 PSIG	0	0.00
Solder DUNK	805	2415	260 °C, 10 s	0	0.00
Solderability	210	1800	883 M2003	0	0.00
Temp. Cycle	1228	934 724	-55 °C to 150 °C	0	0.00